



Material Content Data Sheet



Sales Product Name				TDA21241		Issued		20. July 2018	
MA#				MA001650104					
Package				PG-IQFN-30-2		Weight*		55.72 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.304	2.34	2.34	23411	23411	
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		83		
	non noble metal	zinc	7440-66-6	0.018	0.03		331		
	non noble metal	iron	7439-89-6	0.368	0.66		6610		
wire	non noble metal	copper	7440-50-8	14.956	26.84	27.54	268410	275434	
	non noble metal	copper	7440-50-8	0.085	0.15	0.15	1518	1518	
	encapsulation	organic material	carbon black	1333-86-4	0.047	0.08		834	
glue	plastics	epoxy resin	-	2.395	4.30		42977		
	inorganic material	silicondioxide	60676-86-0	20.809	37.35	41.73	373439	417250	
leadfinish	non noble metal	tin	7440-31-5	0.593	1.06	1.06	10638	10638	
plating	noble metal	silver	7440-22-4	0.040	0.07	0.07	721	721	
glue	plastics	epoxy resin	-	0.088	0.16		1586		
	noble metal	silver	7440-22-4	0.265	0.48	0.64	4758	6344	
solder	noble metal	silver	7440-22-4	0.021	0.04		369		
	non noble metal	tin	7440-31-5	0.041	0.07		738		
	non noble metal	lead	7439-92-1	0.761	1.37	1.48	13661	14768	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		14		
	non noble metal	zinc	7440-66-6	0.003	0.01		55		
	non noble metal	iron	7439-89-6	0.062	0.11		1106		
	non noble metal	copper	7440-50-8	2.502	4.49	4.61	44901	46076	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.01		61		
	non noble metal	zinc	7440-66-6	0.014	0.02		245		
	non noble metal	iron	7439-89-6	0.273	0.49		4892		
	non noble metal	copper	7440-50-8	11.069	19.86	20.38	198642	203840	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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